

**THERMALLY ENHANCED COMPONENT INTERPOSER: FINGER AND
NET STRUCTURES**

ABSTRACT OF THE DISCLOSURE

An IC package dissipates thermal energy using thermally and electrically conductive thermal fingers. The IC package includes a substrate material with a die pad area, which is suitable to support an integrated circuit. A plurality of solder ball pads is disposed on a first surface of the substrate material and a plurality of conductive thermal fingers encompass the die pad area to facilitate the dissemination of thermal energy from the die pad area to the substrate and/or printed wiring board.